

Studies for a Silicon Telescope to extend the magnet facility at the DESY test beam.

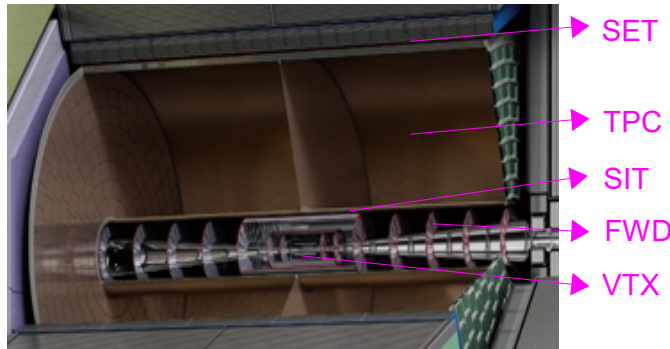
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DPG Frühjahrstagung, 2-Mar-2016



International Large Detector – Tracking Requirements

- > The ILD is one detector concept for the International Linear Collider
- > The ILC is an e^+e^- accelerator up to centre of mass energies of 1TeV



> Momentum resolution:

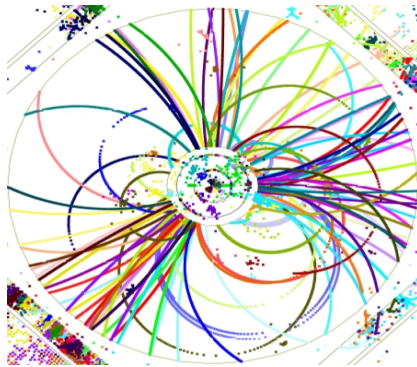
- $\sigma(\Delta p_T/p_T^2) = 2 \cdot 10^{-5} \text{ GeV}^{-1}$ (an order of magnitude better than ATLAS/CMS)
- TPC alone: 10^{-4} GeV^{-1}

200 space points \rightarrow point resolution better than $100 \mu\text{m}$

> Particle Flow

- Low material budget (barrel TPC $5\% X_0$)
- close to 100% tracking efficiency down to low momenta

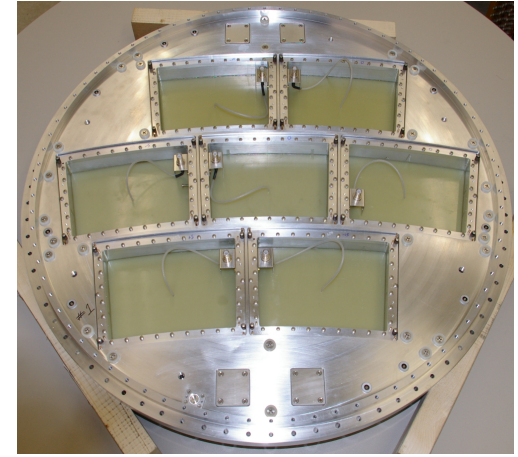
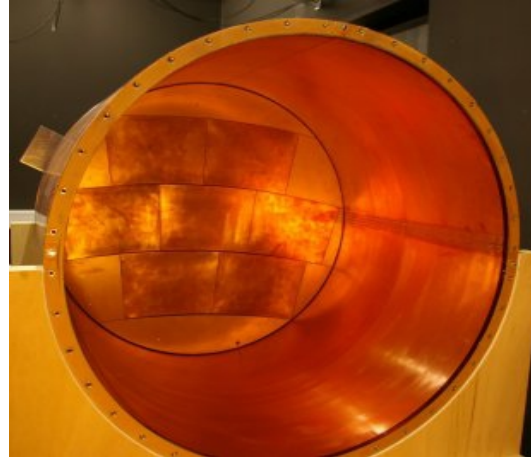
> Full angular coverage and high hermeticity



tTh event

Large Prototype TPC and Current Infrastructure

- > Test beam area T24/1 at DESY (1-6 GeV e^- beams)
- > Large Prototype TPC built and installed
- > Infrastructure includes a large bore 1T magnet
 - 20% X_0 material budget
- > LP field cage parameters:
 - Length: 61 cm, Diameter: 72 cm
 - Wall material budget: 1.3% X_0
- > The endplate is able to host 7 readout modules (dimensions $\sim 22 \times 17$ cm²)

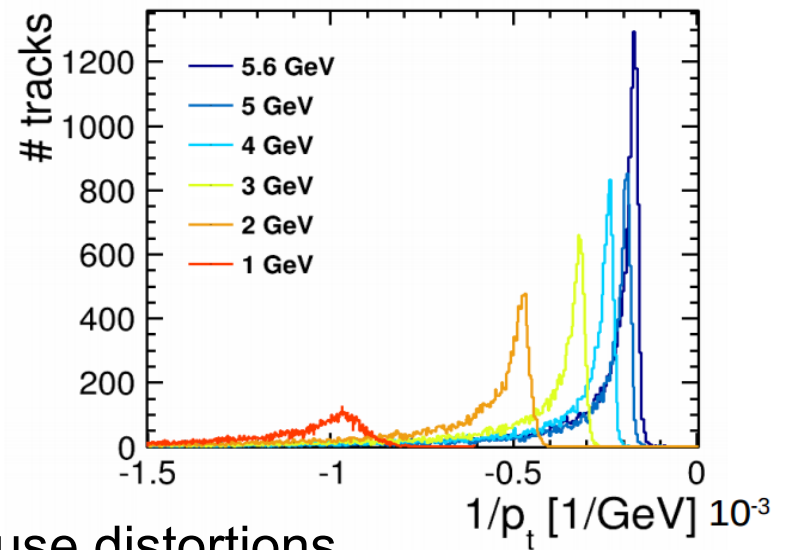


Momentum resolution measurement

- Determination of the momentum resolution in a tracking detector (Gluckstern formula)

$$\sigma_{p_T} = \sqrt{\frac{720}{n+4}} \frac{\sigma \cdot p_T^2}{0.3 B L^2}$$

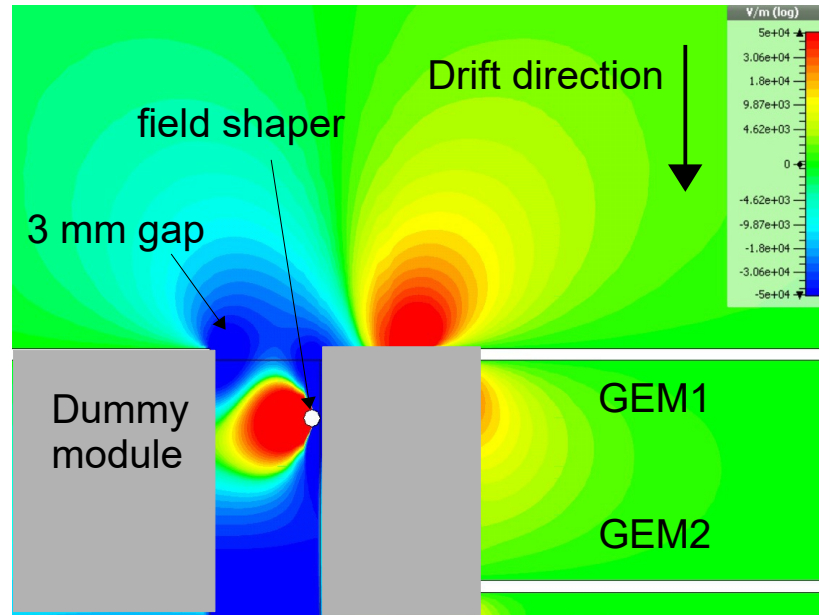
- In the Large Prototype TPC case, there is a broad energy spectra due to the energy loss in the magnet



- In addition, field inhomogenities can cause distortions
- → Hits appear to be displaced
- → This has an impact on the momentum determination



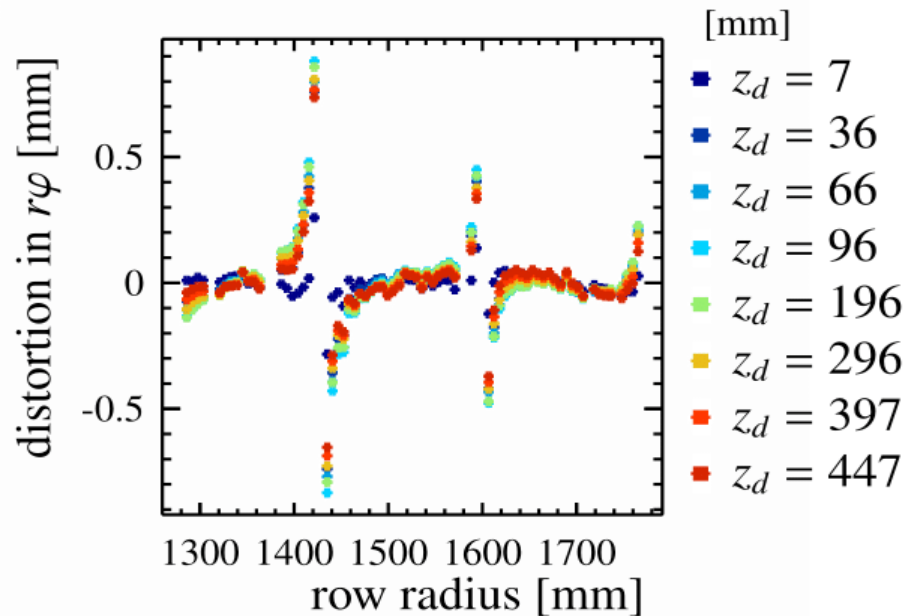
Field distortions in TPC



- > Inhomogenities in Electric fields can cause distortions
- > Magnetic field parallel to the electric field
 - $E \times B$ terms pronounced at module edges

Distortions in TPC tracks

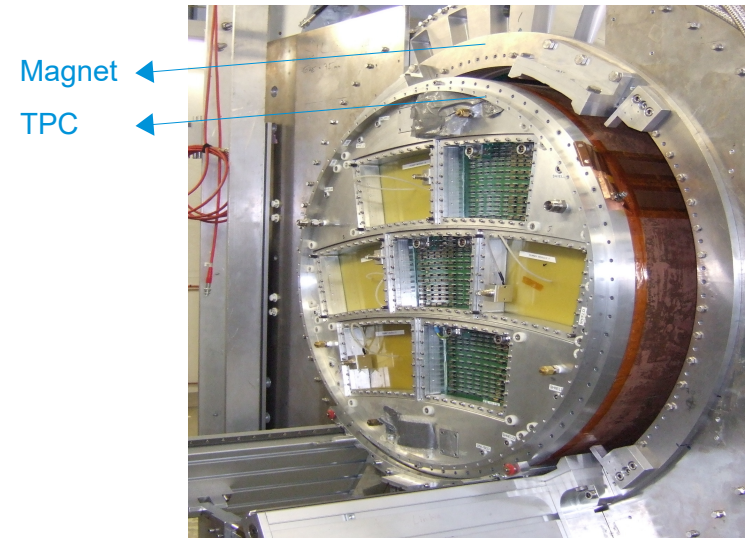
- > Test beam data
- > E and B (1 T) fields present



- > A curved fit (helix) is used for the track → distortions can be partially absorbed in the track curvature

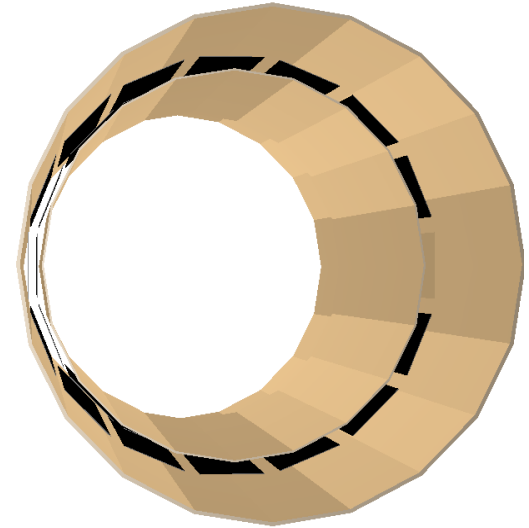
External Si tracker for Large Prototype TPC

- > Solution: Build an external Si tracker (Si telescope) to provide reference tracks (entry and exit hits)
- > Prototype for ILD TPC exists at DESY
- > Goal: Combined test beam with LPTPC → track reference, field distortion corrections, momentum resolution measurements
- > The Silicon tracker should be versatile and simple to be used as a telescope by other groups during test beams
- > Challenge: The Silicon system needs to fit in the existing infrastructure (available space is ~3.5 cm)



The Silicon Tracker Project

- > Simulation studies to determine the general characteristics of the system
 - Number of Silicon layers
 - Distance between the Si layers
 - Material budget
 - possible dimensions of support structure
 - optimal coverage area
- > Hardware options
 - Investigate hardware options to use in terms of sensors (pixels vs strips), chip, DAQ
 - The DAQ system will have to be merged with the current TPC one
- > Design support for the Silicon tracker to fit in the current infrastructure

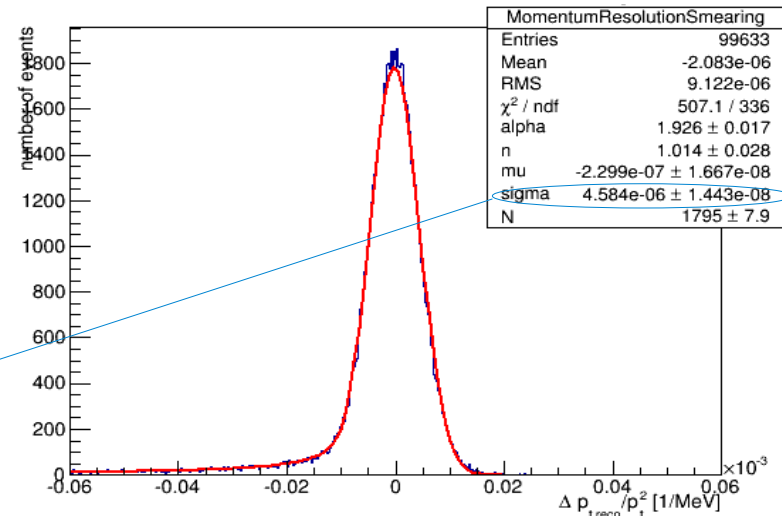


Simulation Studies

- > Simulation Studies to determine the general characteristics of the system
- > Geant4 simulation to include accurate model of the current material budget of the infrastructure
- > For the Si system to be used as a reference, the Si standalone simulated momentum resolution should be better than the TPC one
 - → Criterion used to define the characteristics of the Si system

- > Measuring the momentum resolution in standalone Silicon system and standalone TPC system by fitting a crystal ball function to the simulated points

Standalone TPC simulated momentum resolution is $4.58 \cdot 10^{-6} \text{ MeV}^{-1}$

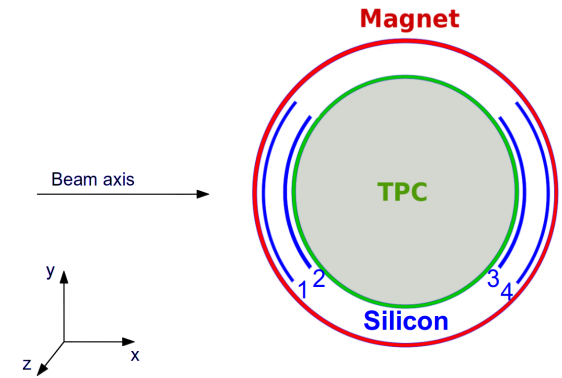


Distance between Si layers

- > Dependence of sensor spatial resolution on distance between layers

- Momentum resolution shown in units of 10^{-6} MeV^{-1}

		Distance between inner and outer Si layer			
		4 cm	3 cm	2 cm	1 cm
Sensor spatial resolution	2.5 μm	2.85	2.90	3.00	3.68
	5 μm	3.05	3.21	3.63	5.52
	7.5 μm	3.37	3.65	4.43	7.92
	10 μm	3.68	4.16	5.33	9.90
	15 μm	4.49	5.36	7.53	14.3

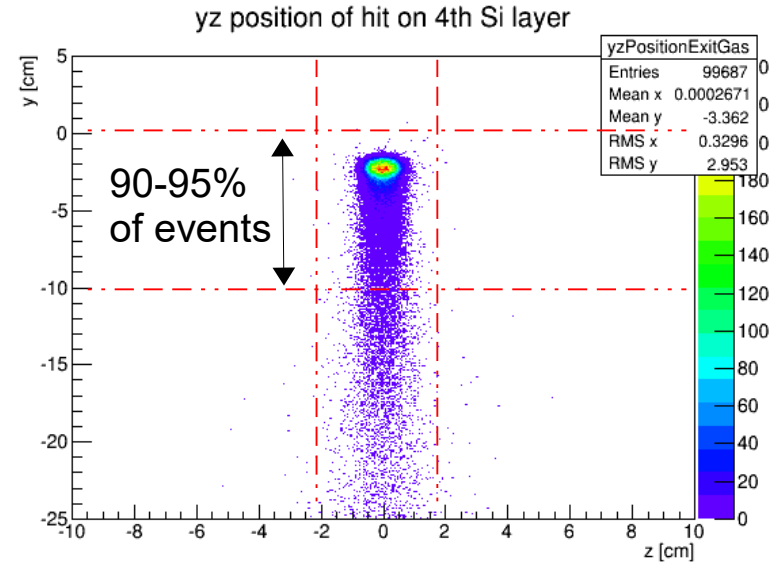
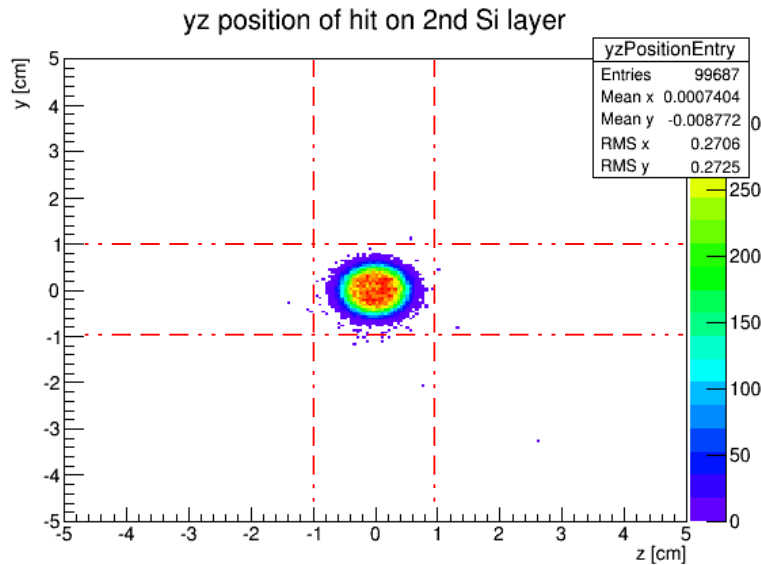


- > Sensors with spatial resolution better than 10 μm are needed

ILC	ATLAS	CMS
<10 μm	12 μm (pixels)	10 μm (pixels)
	16 μm (strips)	20-30 μm (strips)

Coverage area

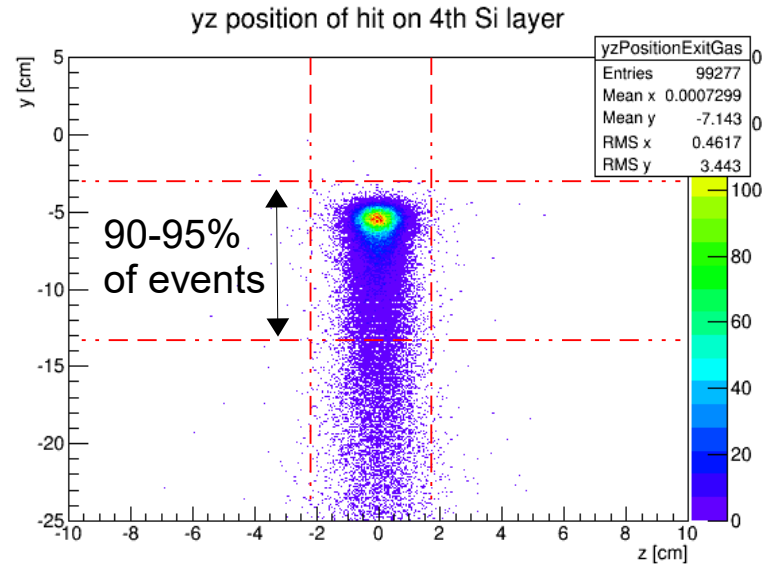
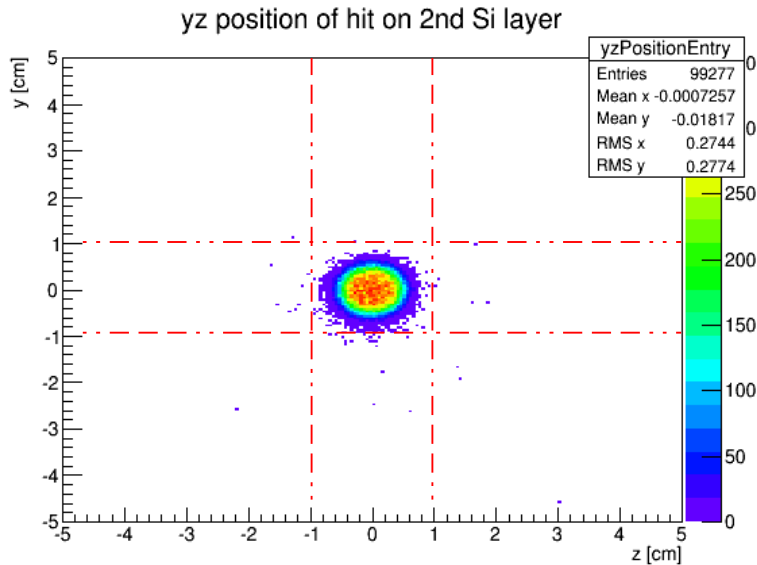
- Hit positions on front and back sensors for 5 GeV e^- beams



- For lower energy beams, the hit distribution on the back sensors is more spread and shifted to lower y values

Coverage area

- Hit positions on front and back sensors for 2 GeV e^- beams



- For lower energy beams, the hit distribution on the back sensors is more spread and shifted to lower y values
- Minimum coverage area: $\sim 2 \times 2 \text{ cm}^2$ for front and $4 \times 10 \text{ cm}^2$ for back sensors
- Larger coverage area is beneficial (e.g. for distortions, less moving and alignment of the system)

Hardware Options

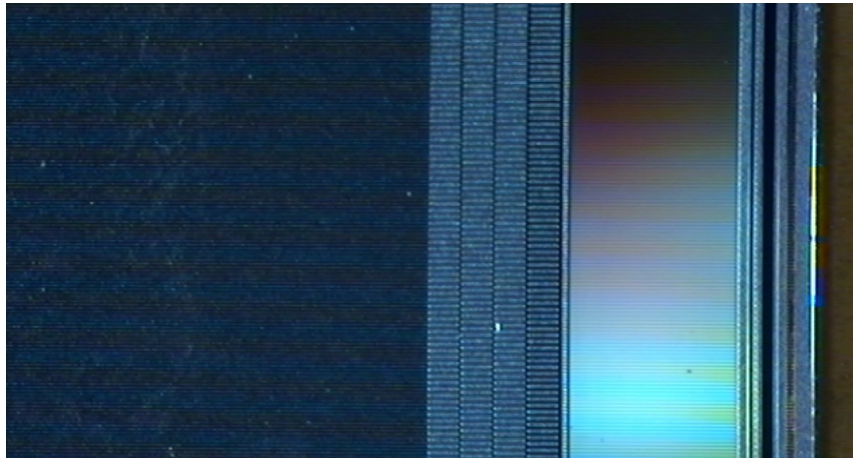
> Strip vs Pixel Silicon sensors

Strip sensors (SiD)

- > Good spatial resolution (7-8 μm)
- > Large sensor surface \rightarrow Able to instrument large areas (eg 10x20 cm^2)
- > Medium cost

Pixel sensors (Mimosa)

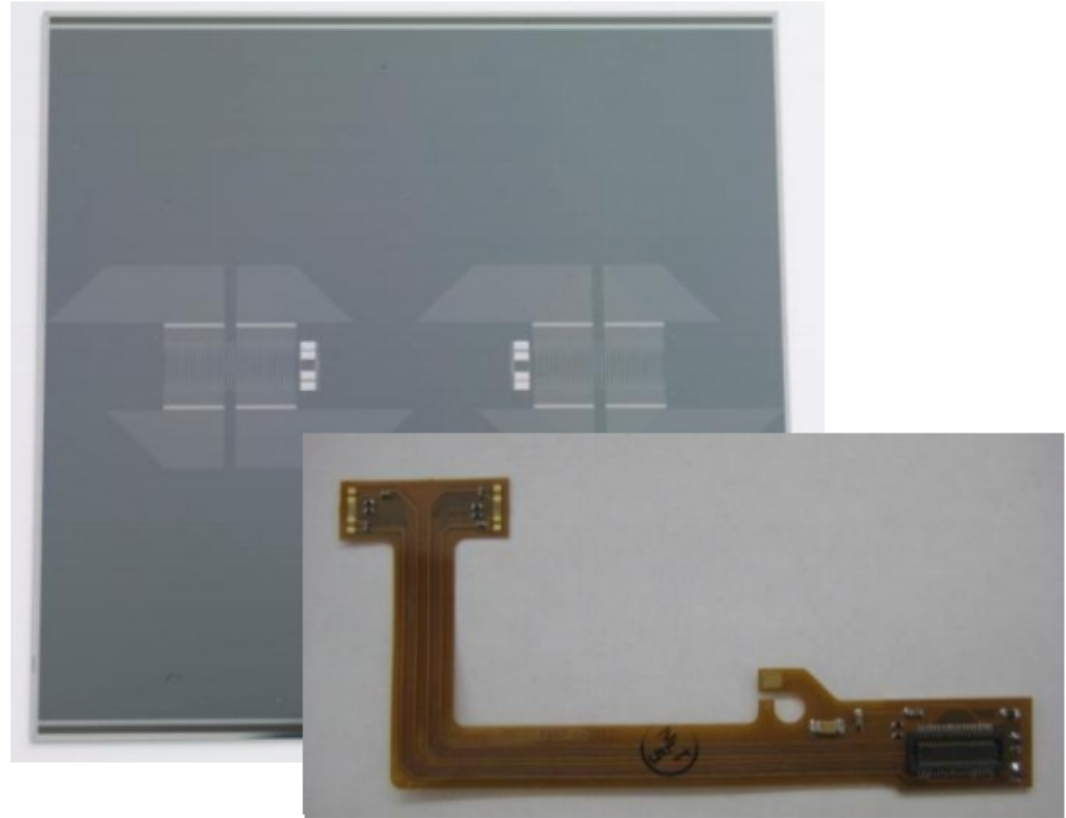
- > Excellent spatial resolution (3-4 μm)
- > Small sensor surface \rightarrow Able to instrument minimum area only
- > High cost



SilC sensor
50 μm pitch

Hardware Options (2)

- Si strip sensors of 25 μm pitch \rightarrow spatial resolution 7-8 μm
- Si sensor dimensions: $\sim 10 \times 10 \text{ cm}^2$
- Read out by two kpix chips bump bonded onto the sensor
- Control of sensor and kpix through wire bonding
- Capton cable to read out the data from kpix and control the kpix and sensor



Summary & Plans

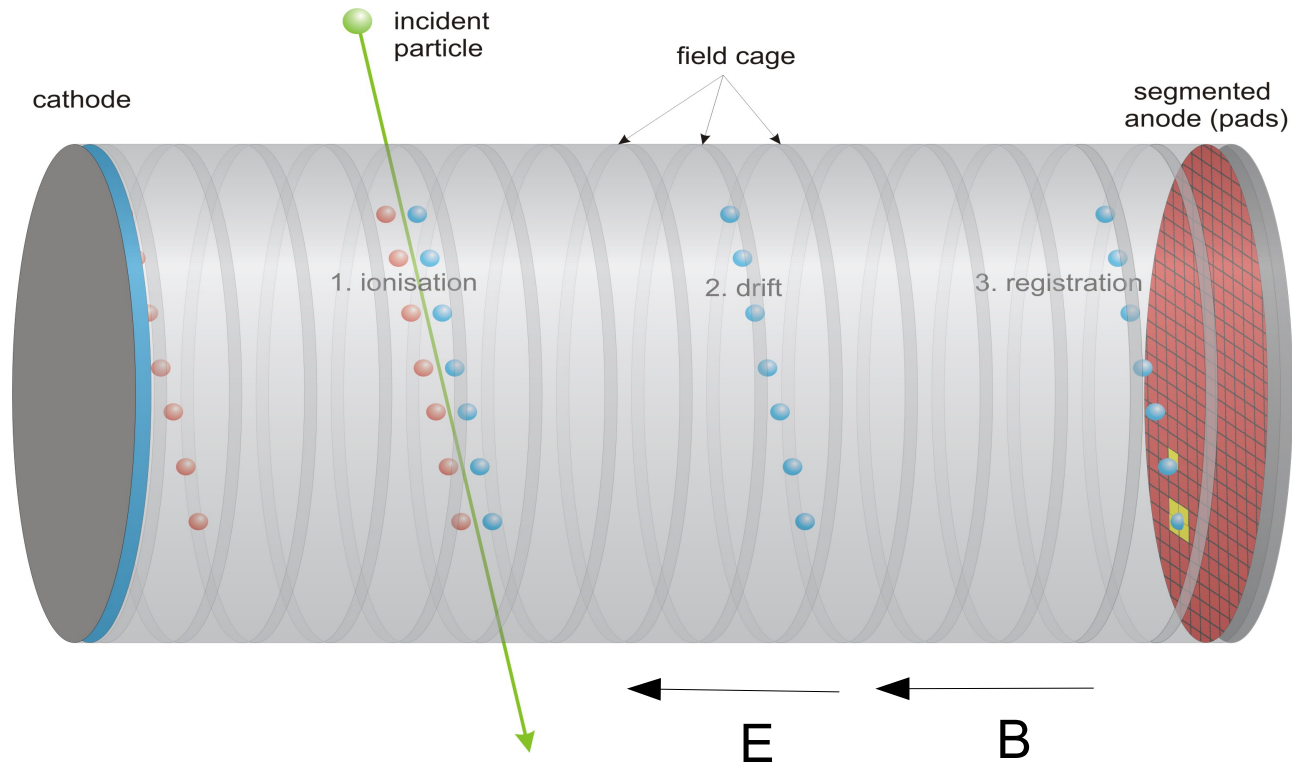
- > Instrumenting T24/1 test beam setup with a Silicon telescope able to fit the requirements of the Large Prototype TPC
- > Simulation studies to determine the characteristics of the Silicon system
- > Sensors with spatial resolution better than $10\ \mu\text{m}$ needed
- > Large surface area desirable
- > Plans to acquire hardware within the next months (1 month for ASIC, 3-4 months for sensors)
- > Ongoing simulation studies within the ILC framework (DD4hep)
- > Design process for Silicon system support



Back-Up



Time Projection Chamber – Working Principle



- > Magnetic field parallel to the electric field
- > Inhomogeneities in Electric & Magnetic fields can cause distortions (ExB terms)